

# EA3250HA08-14.7456M



## ITEM DESCRIPTION

Quartz Crystal Resonator 3.2mm x 5.0mm x 1.0mm 4 Pad Ceramic Surface Mount (SMD) 14.7456MHz  $\pm 15$ ppm at 25°C,  $\pm 30$ ppm over -20°C to +70°C 08pF Parallel Resonant

## ELECTRICAL SPECIFICATIONS

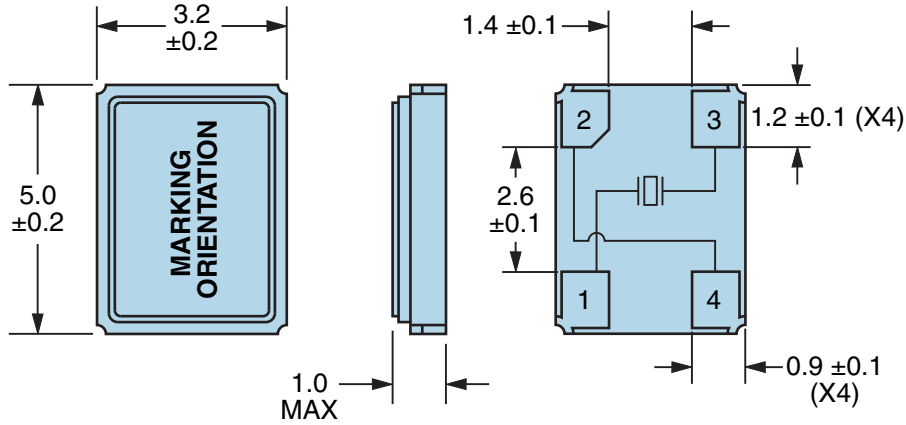
Nominal Frequency	14.7456MHz
Frequency Tolerance/Stability	$\pm 15$ ppm at 25°C, $\pm 30$ ppm over -20°C to +70°C
Aging at 25°C	$\pm 3$ ppm/Year Maximum
Load Capacitance	08pF Parallel Resonant
Shunt Capacitance	5pF Maximum
Equivalent Series Resistance	55 Ohms Maximum
Mode of Operation	AT-Cut Fundamental
Drive Level	100 $\mu$ Watts Maximum
Spurious Response	-3dB Minimum (Measured from Fo to Fo+5000ppm)
Storage Temperature Range	-40°C to +125°C
Insulation Resistance	500 Megaohms Minimum (Measured at 100Vdc)

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

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## MECHANICAL DIMENSIONS (all dimensions in millimeters)

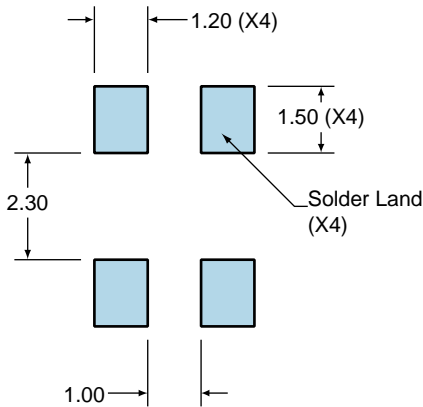


PIN	CONNECTION
1	Crystal
2	Cover/Ground
3	Crystal
4	Cover/Ground

LINE	MARKING
1	<b>E14.74</b> <i>E=Ecliptek Designator</i>
2	<b>XXXXX</b> <i>XXXXX=Ecliptek Manufacturing Identifier</i>

## Suggested Solder Pad Layout

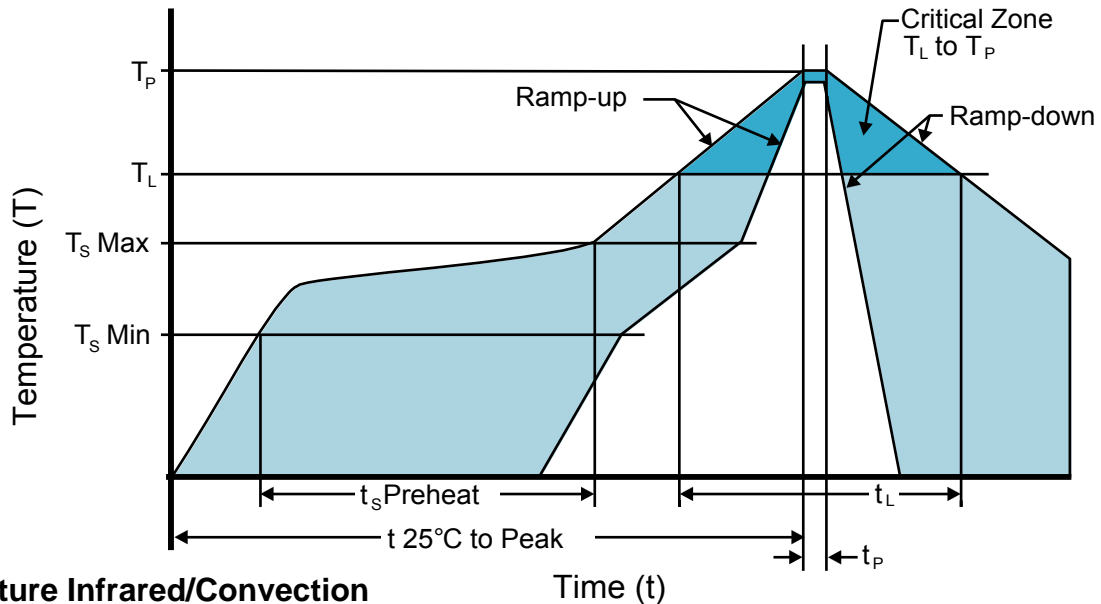
All Dimensions in Millimeters



All Tolerances are ±0.1

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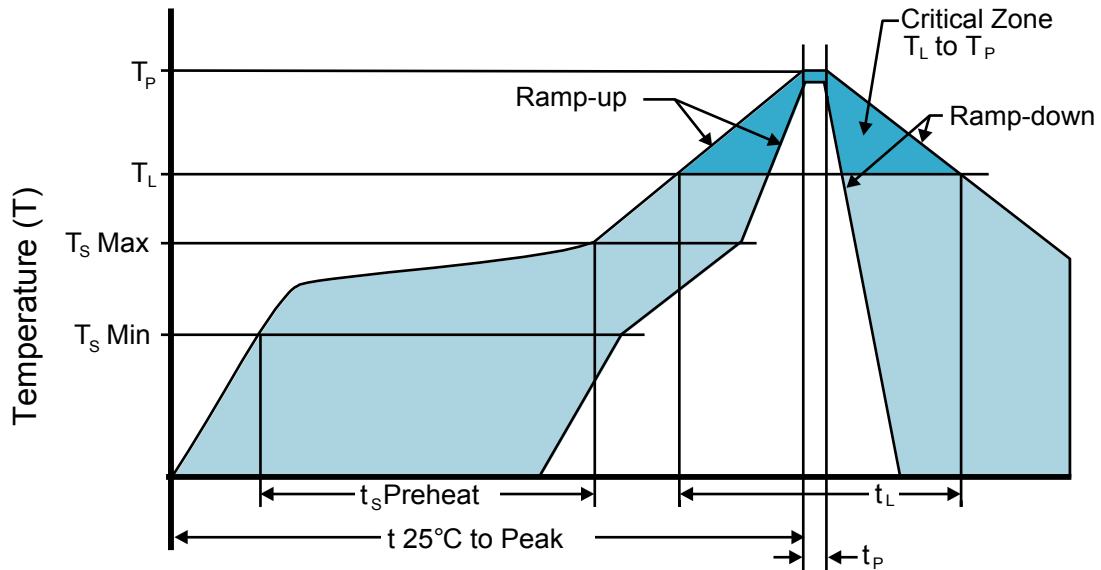
## Recommended Solder Reflow Methods

**High Temperature Infrared/Convection**

<b><math>T_s</math> MAX to <math>T_L</math> (Ramp-up Rate)</b>	3°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum ( $T_s$ MIN)	150°C
- Temperature Typical ( $T_s$ TYP)	175°C
- Temperature Maximum ( $T_s$ MAX)	200°C
- Time ( $t_s$ MIN)	60 - 180 Seconds
<b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>	3°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	217°C
- Time ( $t_L$ )	60 - 150 Seconds
<b>Peak Temperature (<math>T_P</math>)</b>	260°C Maximum for 10 Seconds Maximum
<b>Target Peak Temperature (<math>T_P</math> Target)</b>	250°C +0/-5°C
<b>Time within 5°C of actual peak (<math>t_p</math>)</b>	20 - 40 Seconds
<b>Ramp-down Rate</b>	6°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	8 Minutes Maximum
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to body of device.

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## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 245°C

**T<sub>s</sub> MAX to T<sub>L</sub> (Ramp-up Rate)** 5°C/Second Maximum

#### Preheat

- Temperature Minimum (T<sub>s</sub> MIN) N/A
- Temperature Typical (T<sub>s</sub> TYP) 150°C
- Temperature Maximum (T<sub>s</sub> MAX) N/A
- Time (t<sub>s</sub> MIN) 30 - 60 Seconds

**Ramp-up Rate (T<sub>L</sub> to T<sub>P</sub>)** 5°C/Second Maximum

#### Time Maintained Above:

- Temperature (T<sub>L</sub>) 150°C
- Time (t<sub>L</sub>) 200 Seconds Maximum

**Peak Temperature (T<sub>P</sub>)** 245°C Maximum

**Target Peak Temperature (T<sub>P</sub> Target)** 245°C Maximum 2 Times / 230°C Maximum 1 Time

**Time within 5°C of actual peak (t<sub>p</sub>)** 10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time

**Ramp-down Rate** 5°C/Second Maximum

**Time 25°C to Peak Temperature (t)** N/A

**Moisture Sensitivity Level** Level 1

**Additional Notes** Temperatures shown are applied to body of device.

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device. )

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device. )